Connectors to Power Board

- J3 is connected to J4 (Input Driver B) or J6 (Input Driver A)
- J4 on Power Board
  J4–2: P1.1 of MSP430 (Pin 3)
  J4–3: P1.6 of MSP430 (Pin 8)
- J6 on Power Board
  J6–2: P1.2 of MSP430 (Pin 4)
  J6–3: P1.5 of MSP430 (Pin 7)
- J4 is connected to J5 (Gate high-side FET B) or J7 (Gate high-side FET A)

Notes

- Built on PCB "PMP5568 – 350W PSU – Gate Drive RevA.pcb"
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